

## FABRICATION PARAMETERS:

THICKNESS: SILKSCREEN: SOLDERMASK: COPPER WEIGHT: DESIGN TYPE: MIN TRACE/GAP: LAYER COUNT:

0.062 BOTH BOTH 2 OZ (EXT) /2 OZ (INT) MIX 0.005/0.005 6 LAYERS

## NOTES: UNLESS OTHERWISE SPECIFIED

ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-190 REQUIREMENTS AND BE 804S COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0. PLASTIC SHEET, LAMINATED METAL CLAD, THO SIDES, BASE MATERIAL NEWA TYPE FR-4 GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 8 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH 16-CS-M-8-GO. HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 0Z. (0.0014) MIN. THK MIN. THICK COPPER. 1. MATERIAL: 2. BASE LAMINATE:

3. SOLDERMASK:

4. PLATING:

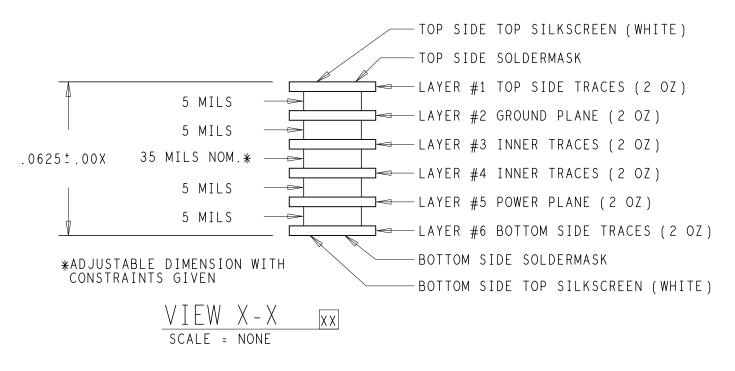
HOLES REQUIRING PLATTING, SEE HOLE CHART, TO HAVE I OZ. (0.0014) MIN. THK MIN. THICK COPPER. 
PLATE WITH ROHS COMPLIANT, IMMERSION SILVER PREFERED, IMMERSION TIN OR Sn/Ag/Cu, 
WITH RMA FLUX, 0.0005' -/- 0.0003' THICK MIN ALL EXPOSED AREAS 
AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE. 
IF REQUIRED, SILKSCREIN LEGENQS SWITH WHITE NON-CONDUCTIVE EPOXY INK. 
BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK), 
LOCATION OPTIONAL. 
PC BOARD SHALL BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER. 
PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS 
INSTRIBMENTS UPON COMPLETION OF PURCHASE ORDER. 
HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED. 
ANY METAL IN BOORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS 
MUST BE COVERED WITH SOLDEMENSS.

6. LEGEND: 7. MARKINGS:

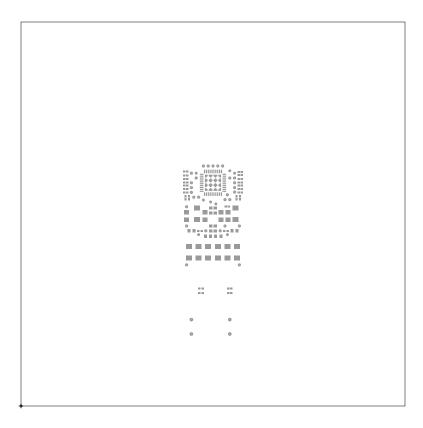
8. WORKMANSHIP: 9. DOCUMENTATION:

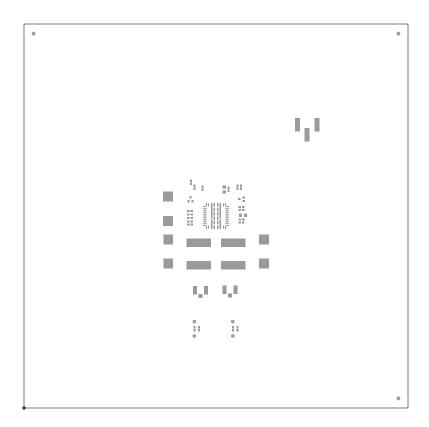
MUST BE COVERED WITH SOLDERMASK.

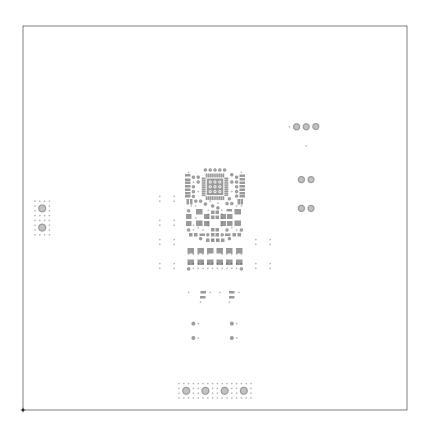
12. PROCESS CHANGES NO DIMENSIONAL. MATERIAL. OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS

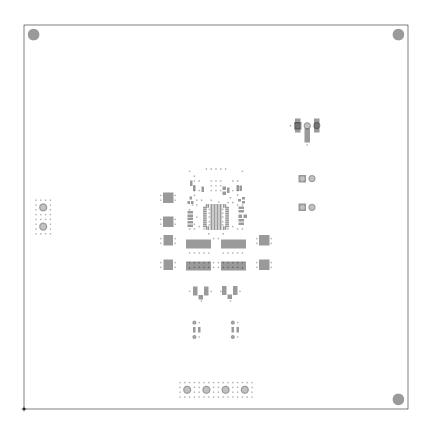


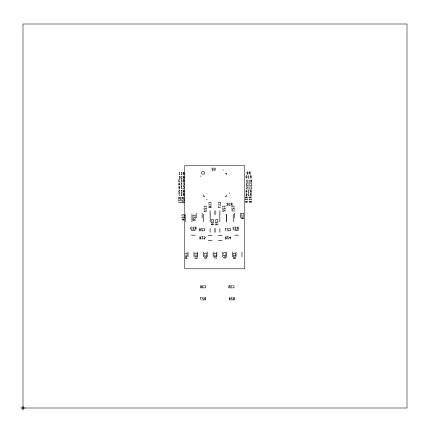
DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
8	10.0	+2.0/-7.0	PLATED	42
8	10.0	+3.0/-3.0	PLATED	169
*	50.0	+3.0/-3.0	PLATED	7
*	60.0	+3.0/-3.0	PLATED	6

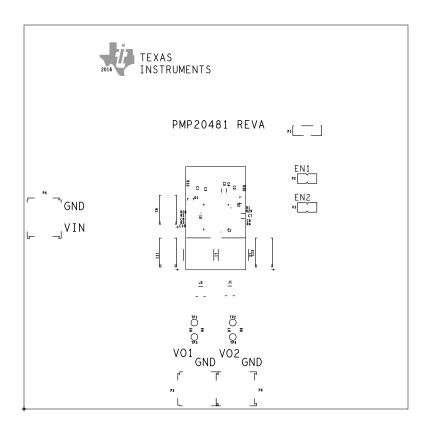


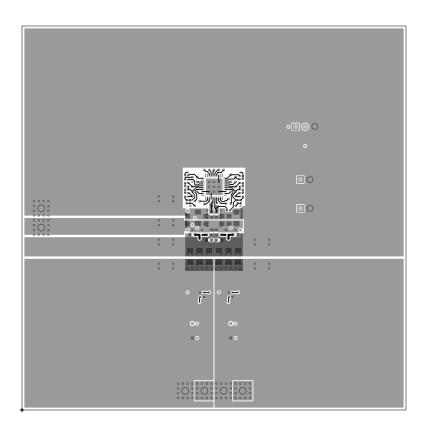


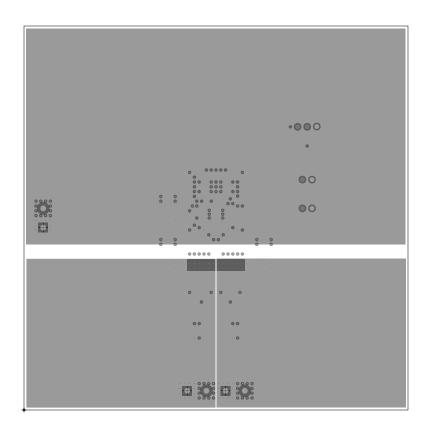


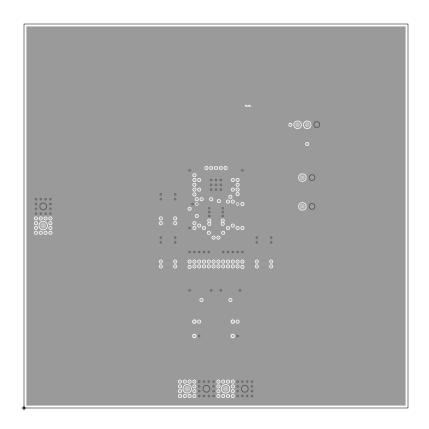


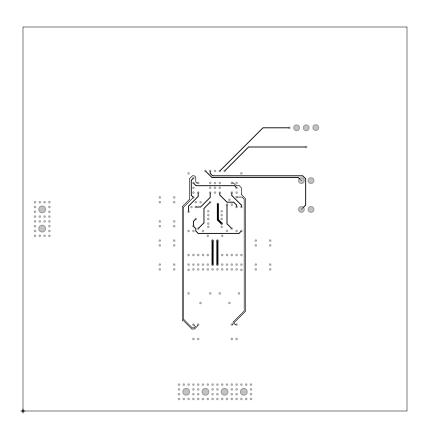


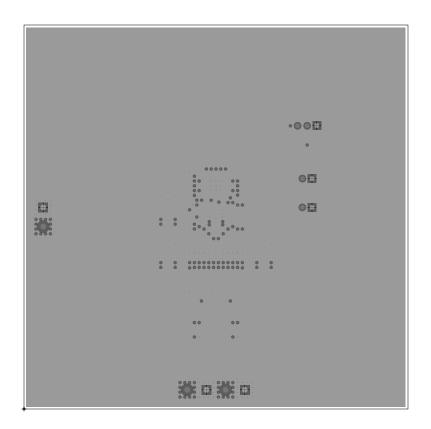


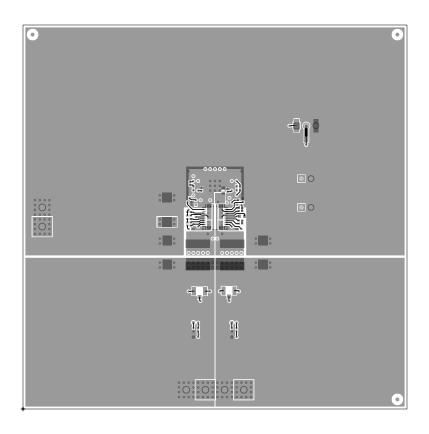












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